

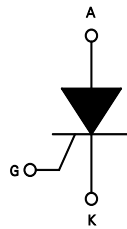
SxX8BBS Series



Main Features

Symbol	Value	Unit
$I_{T(RMS)}$	0.8	A
V_{DRM}/V_{RRM}	600	V
I_{GT}	200	μA

Schematic Symbol



Description

This new sensitive SCR component series offers 600V V_{DRM} and 0.8A $I_{T(RMS)}$ capability in the smallest package size in the industry, SOT23. It is specifically designed for GFCI (Ground Fault Circuit Interrupter) applications. All SCRs junctions are glass-passivated to ensure long term reliability and parametric stability.

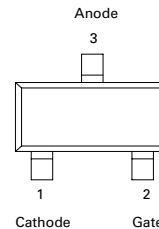
Features

- Very compact SOT23 SMT package
- Surge current capability up to 12A @ 60Hz
- Blocking voltage (V_{DRM}/V_{RRM}) capability - up to 600V
- High dv/dt noise immunity
- Improved turn-off time (t_q) < 25 μsec
- Sensitive gate for direct microprocessor interface
- RoHS compliant and Halogen-Free

Applications

The SxX8BBS series is specifically designed for GFCI (Ground Fault Circuit Interrupter) and applications.

Pin out



Absolute Maximum Ratings

Symbol	Parameter	Value	Unit	
V_{DSM}/V_{RSM}	Peak non-repetitive blocking voltage	Pw=100 μs	700 V	
$I_{T(RMS)}$	RMS on-state current (full sine wave)	$T_C = 80^\circ C$	0.8 A	
$I_{T(AV)}$	Average on-state current	$T_C = 80^\circ C$	0.51 A	
I_{TSM}	Non repetitive surge peak on-state current (Single cycle, $T_{J\ initial} = 25^\circ C$)	f= 50Hz	10 A	
		f= 60Hz	12 A	
I^2t	I ² t Value for fusing	$t_p = 10\ ms$	f= 50 Hz	0.5 A ² s
		$t_p = 8.3\ ms$	f= 60 Hz	0.6 A ² s
di/dt	Critical rate of rise of on-state current $I_G = 10mA$	60 Hz	$T_J = 125^\circ C$	80 A/ μs
I_{GM}	Peak Gate Current	$t_p = 20\ \mu s$	$T_J = 125^\circ C$	1.0 A
$P_{G(AV)}$	Average gate power dissipation	—	$T_J = 125^\circ C$	0.1 W
T_{stg}	Storage junction temperature range	—	—	-40 to 150 $^\circ C$
T_J	Operating junction temperature range	—	—	-40 to 125 $^\circ C$

Electrical Characteristics ($T_J = 25^\circ\text{C}$, unless otherwise specified)

Symbol	Description	Test Conditions	Limit	Value	Unit
I_{GT}	DC Gate Trigger Current	$V_D = 6V, R_L = 100 \Omega$	MIN.	50	μA
			MAX.	200	μA
V_{GT}	DC Gate Trigger Voltage	$V_D = 6V, R_L = 100 \Omega$	MAX.	0.8	V
V_{GRM}	Peak Reverse Gate Voltage	$I_{RG} = 10\mu\text{A}$	MIN.	8	V
I_H	Holding Current	Initial Current = 20mA	MAX.	10	mA
(dv/dt)s	Critical Rate-of-Rise of Off-State Voltage	$T_J = 125^\circ\text{C}$ $V_D = 67\%V_{DRM}, V_{RRM}$ Exp. Waveform, $R_{GK} = 1 \text{ k}\Omega$	MIN.	50	V/ μs
V_{GD}	Gate Non-Trigger Voltage	$V_D = V_{DRM}, R_{GK} = 1 \text{ k}\Omega$ $T_J = 125^\circ\text{C}$	MIN.	0.2	V
t_q	Turn-Off Time	$I_T = 0.5\text{A}$	MAX.	25	μs
t_{gt}	Turn-On Time	$I_G = 10\text{mA}, P_w = 15\mu\text{sec},$ $I_T = 1.6\text{A(pk)}$	TYP.	2.0	μs

Static Characteristics ($T_J = 25^\circ\text{C}$, unless otherwise specified)

Symbol	Description	Test Conditions	Limit	Value	Unit
V_{TM}	Peak On-State Voltage	$I_{TM} = 1.6\text{A (pk)}$	MAX.	1.70	V
I_{DRM}/I_{RRM}	V_{DRM}/V_{RRM}	$T_J = 25^\circ\text{C}$	MAX.	5	μA
		$T_J = 125^\circ\text{C}$	MAX.	100	μA

Thermal Resistances

Symbol	Description	Value	Unit
$R_{\theta(JC)}$	Junction to case (AC)	45	$^\circ\text{C/W}$
$R_{\theta(JA)}$	Junction to ambient	220	$^\circ\text{C/W}$

Figure 1: Normalized DC Gate Trigger Current vs. Junction Temperature

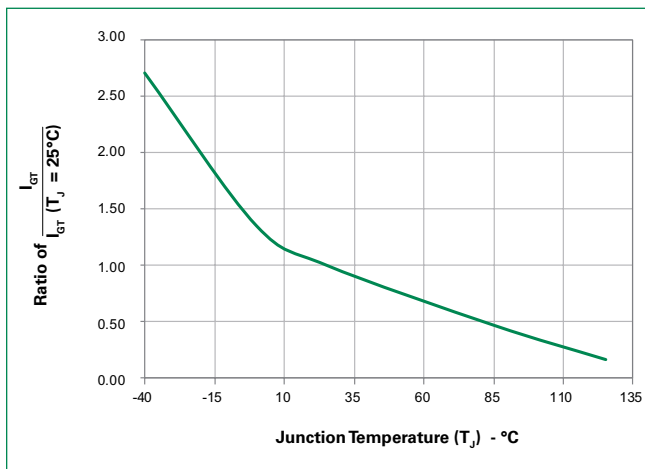


Figure 2: Normalized DC Holding Current vs. Junction Temperature

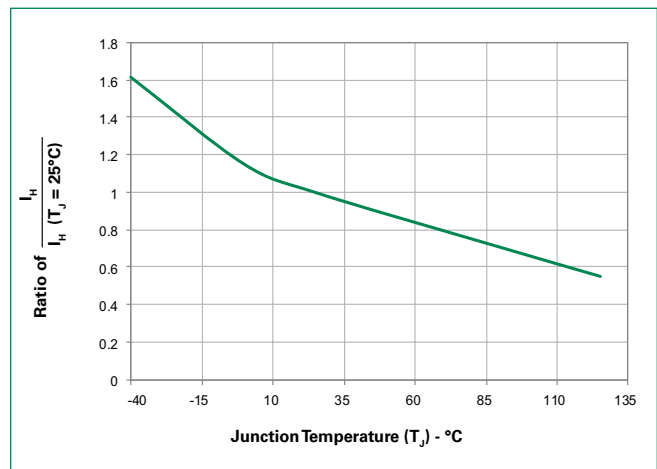


Figure 3: Normalized DC Gate Trigger Voltage vs. Junction Temperature

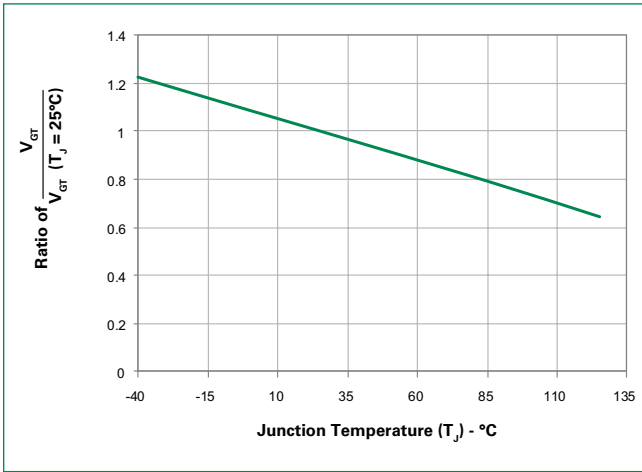


Figure 4: On-State Current vs. On-State Voltage (Typical)

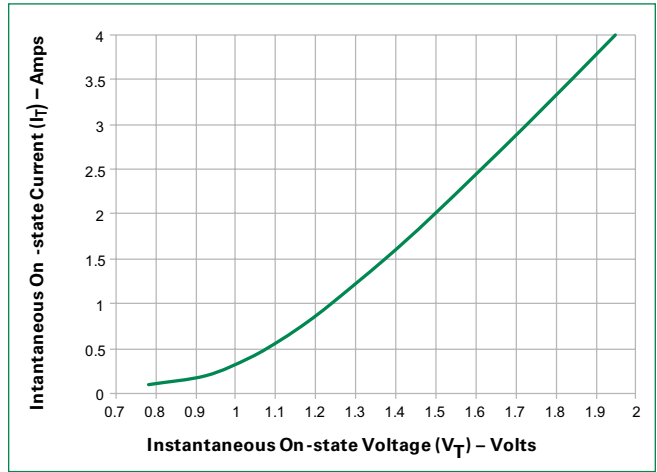


Figure 5: Power Dissipation (Typical) vs. RMS On-State Current

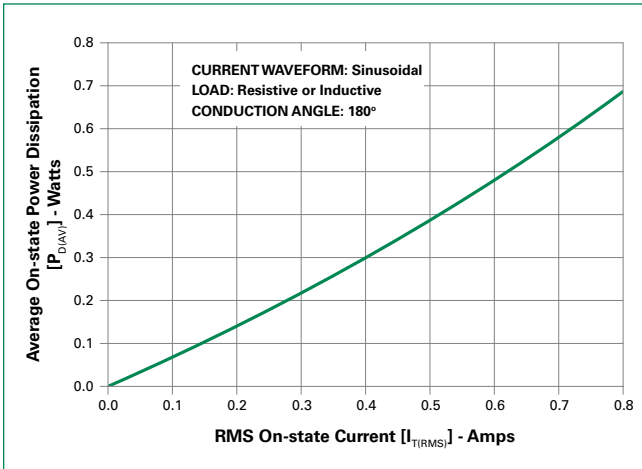


Figure 6: Maximum Allowable Case Temperature vs. On-State Current

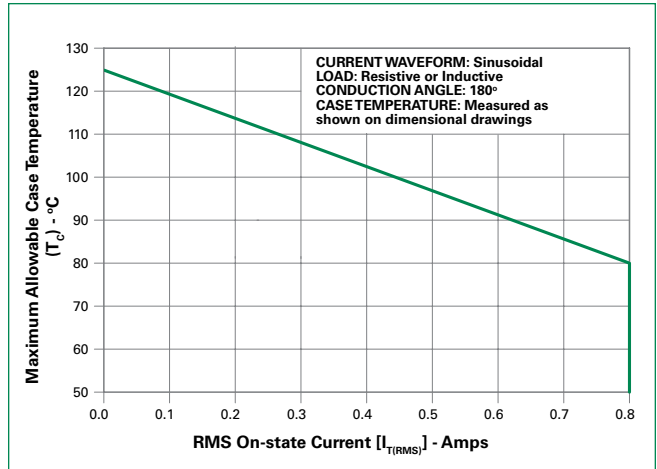


Figure 7: Surge Peak On-State Current vs. Number of Cycles

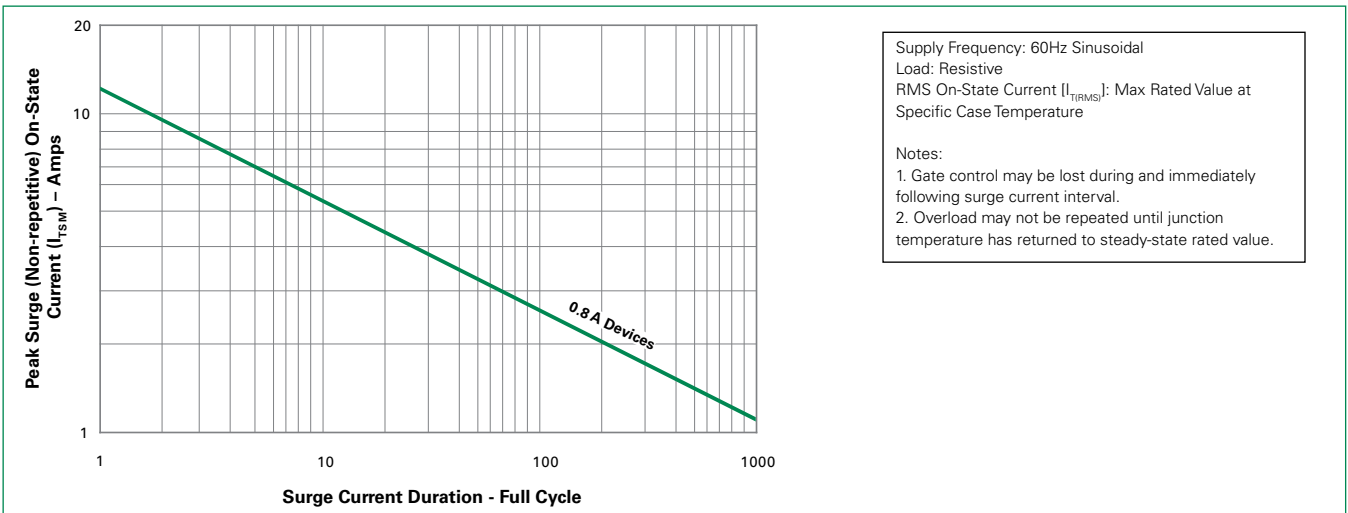


Figure 8: Static dv/dt vs. RGK vs. Junction Temperature

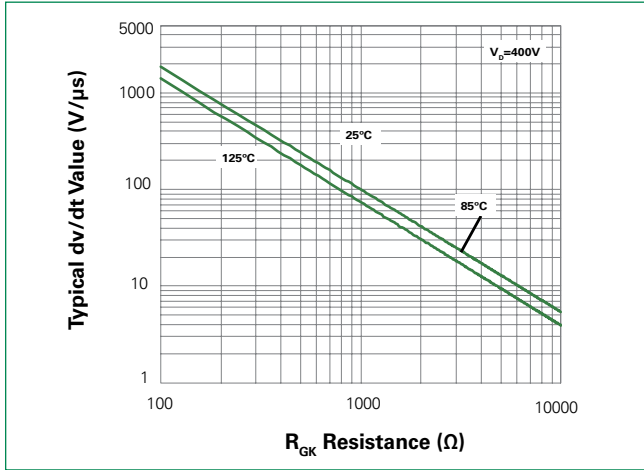
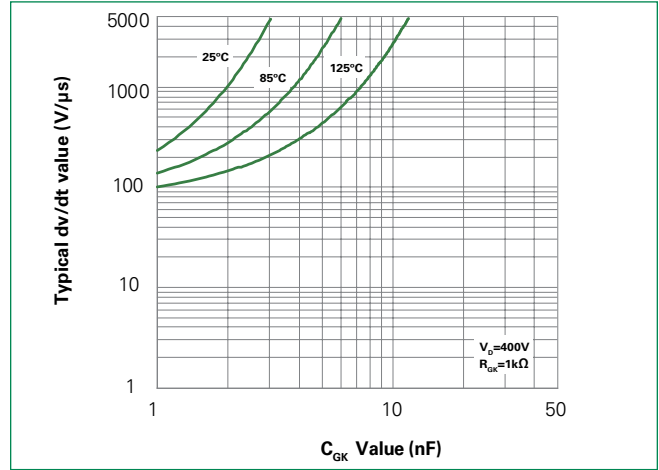
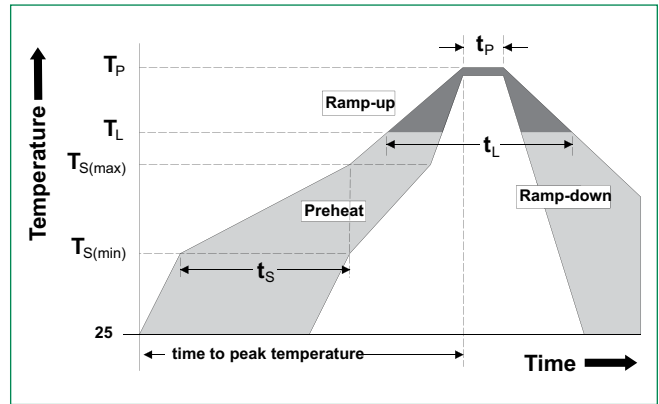


Figure 9: Static dv/dt vs. CGK vs. Junction Temperature



Soldering Parameters

Reflow Condition		Pb – Free assembly
Pre Heat	- Temperature Min ($T_{s(min)}$)	150°C
	- Temperature Max ($T_{s(max)}$)	200°C
	- Time (min to max) (t_s)	60 – 180 secs
Average ramp up rate (Liquidus Temp) (T_L) to peak		5°C/second max
$T_{s(max)}$ to T_L - Ramp-up Rate		5°C/second max
Reflow	- Temperature (T_L) (Liquidus)	217°C
	- Time (min to max) (t_s)	60 – 150 seconds
Peak Temperature (T_p)		260 ^{+0/-5} °C
Time within 5°C of actual peak Temperature (t_p)		20 – 40 seconds
Ramp-down Rate		5°C/second max
Time 25°C to peak Temperature (T_p)		8 minutes Max.
Do not exceed		280°C



Physical Specifications

Terminal Finish	100% Matte Tin-plated.
Body Material	UL Recognized compound meeting flammability rating V-0.
Lead Material	Copper Alloy

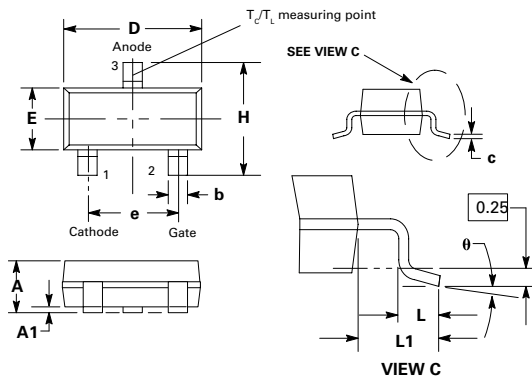
Design Considerations

Careful selection of the correct component for the application's operating parameters and environment will go a long way toward extending the operating life of the Thyristor. Good design practice should limit the maximum continuous current through the main terminals to 75% of the component rating. Other ways to ensure long life for a power discrete semiconductor are proper heat sinking and selection of voltage ratings for worst case conditions. Overheating, overvoltage (including dv/dt), and surge currents are the main killers of semiconductors. Correct mounting, soldering, and forming of the leads also help protect against component damage.

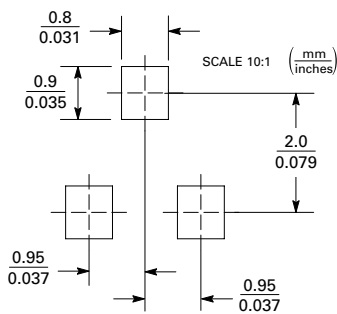
Reliability/Environmental Tests

Test	Specifications and Conditions
HTRB (AC Blocking)	MIL-STD-750, M-1040, Cond A Applied Peak AC voltage @ V_{DRM} @ 125°C for 1008 hours
Temperature Cycling	MIL-STD-750, M-1051, 100 cycles; -55°C to +150°C; 15-min dwell-time
H3TRB	EIA / JEDEC, JESD22-A101 1008 hours; 160V - DC: 85°C; 85% rel humidity
UHASt	ESD22-A118, 96hours, 130°C, 85%RH
Resistance to Solder Heat	MIL-STD-750 Method 2031, 260°C, 10s
Solderability	ANSI/J-STD-002, category 3, Test A
Moisture Sensitivity Level	Level 1, JEDEC-J-STD-020D

Dimensions – SOT-23



SOLDERING FOOTPRINT



Dimensions	Inches			Millimeters		
	Min	Typ	Max	Min	Typ	Max
A	0.035	0.040	0.044	0.89	1.02	1.12
A1	0.001	0.002	0.004	0.03	0.05	0.10
b	0.015	0.018	0.020	0.38	0.46	0.51
c	0.003	0.005	0.007	0.08	0.13	0.18
D	0.110	0.114	0.120	2.79	2.90	3.05
E	0.047	0.051	0.055	1.19	1.30	1.40
e	0.070	0.075	0.081	1.78	1.91	2.06
L	0.004	0.008	0.012	0.10	0.20	0.30
L1	0.014	0.021	0.029	0.36	0.53	0.74
H	0.083	0.094	0.104	2.11	2.39	2.64
θ	0°	-	10°	0°	-	10°

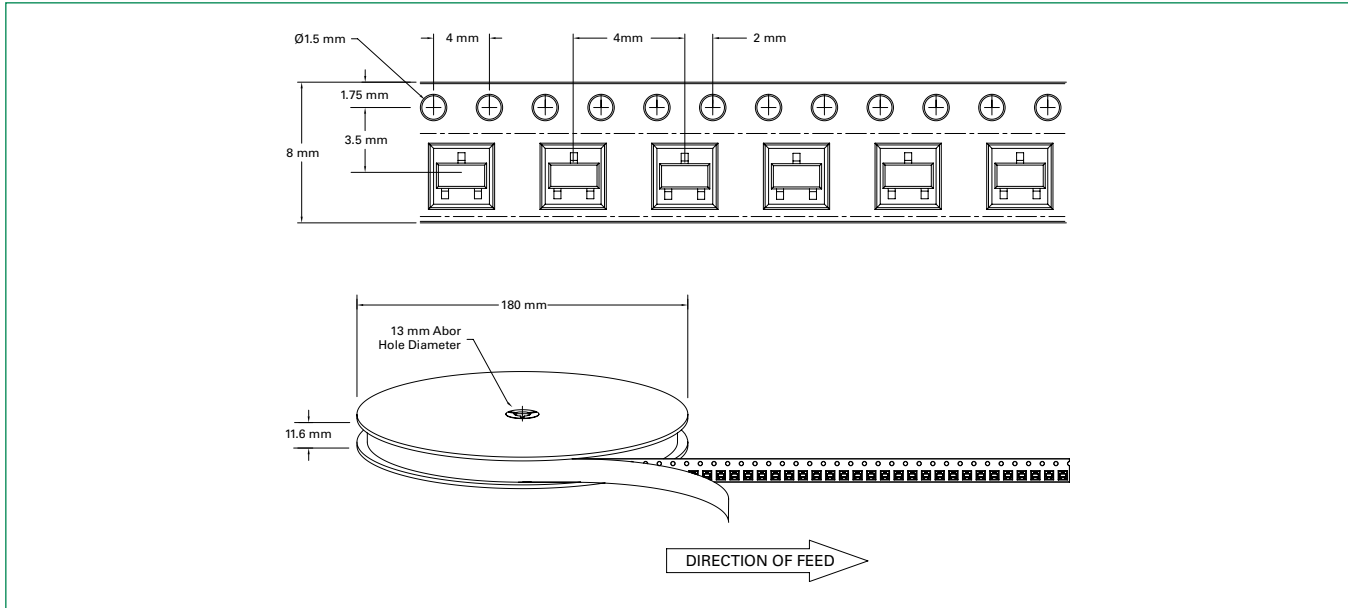
Product Selector

Part Number	Voltage	Gate Sensitivity	Package
	600V		
S6X8BBS	X	200 μ A	SOT-23

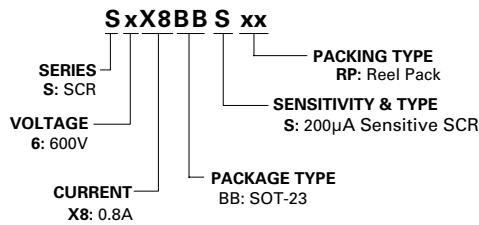
Packing Options

Part Number	Marking	Weight	Packing Mode	Base Quantity
S6X8BBSRP	6X8	0.01g	Tape & Reel	3000

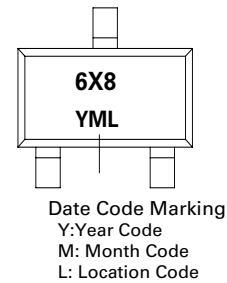
SOT-23 Reel Pack (RP) Specifications



Part Numbering System



Part Marking System



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